

No.	Item	Capability
1	Board Size	2"*4"-18"*20"
2	Board Thickness	0.5-4.0mm or Less
3	SMT Component Size	1.0*0.5mm-74*74mm
4	Component Qty.	Up to 6500 SMD/Board
5	IC Pitch	0.3mm (12mil)
6	BGA /CSP	Pitch 0.35mm
7	Board Complexity	SMT/PTH/Boxbuild
		Single/Double Sides Reflow
8	Glue	Yes
9	Nitrogen Reflow/Wave	Yes
10	Process	Clean/No Clean/Lead Free
11	Baking Oven	Yes
12	BGA Inspection/Rework	Yes